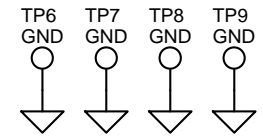


ALL DA* PAIRS MUST BE MATCHED LENGTH

100 OHM DIFF MATCHED LENGTH



NOTES:
1) DNI = DO NOT INSTALL

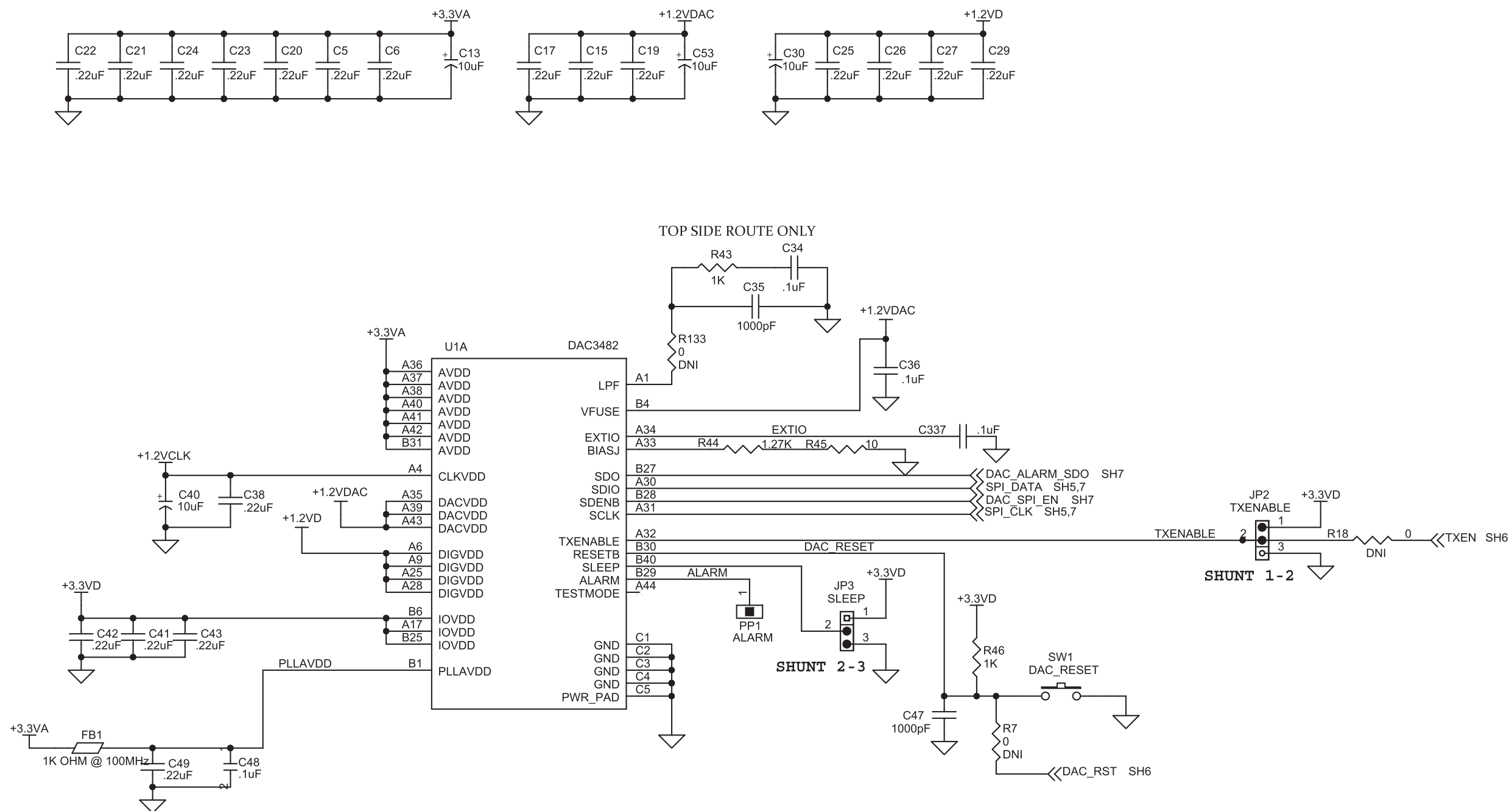
TEXAS INSTRUMENTS

Title: **TSW3085 EVM**

Size: **B** Document Number: **DAC** Rev: **D**

Date: 09Jul12 Sheet 1 of 8

Drawn: L. Nguyen
Engineer: K. Hsia



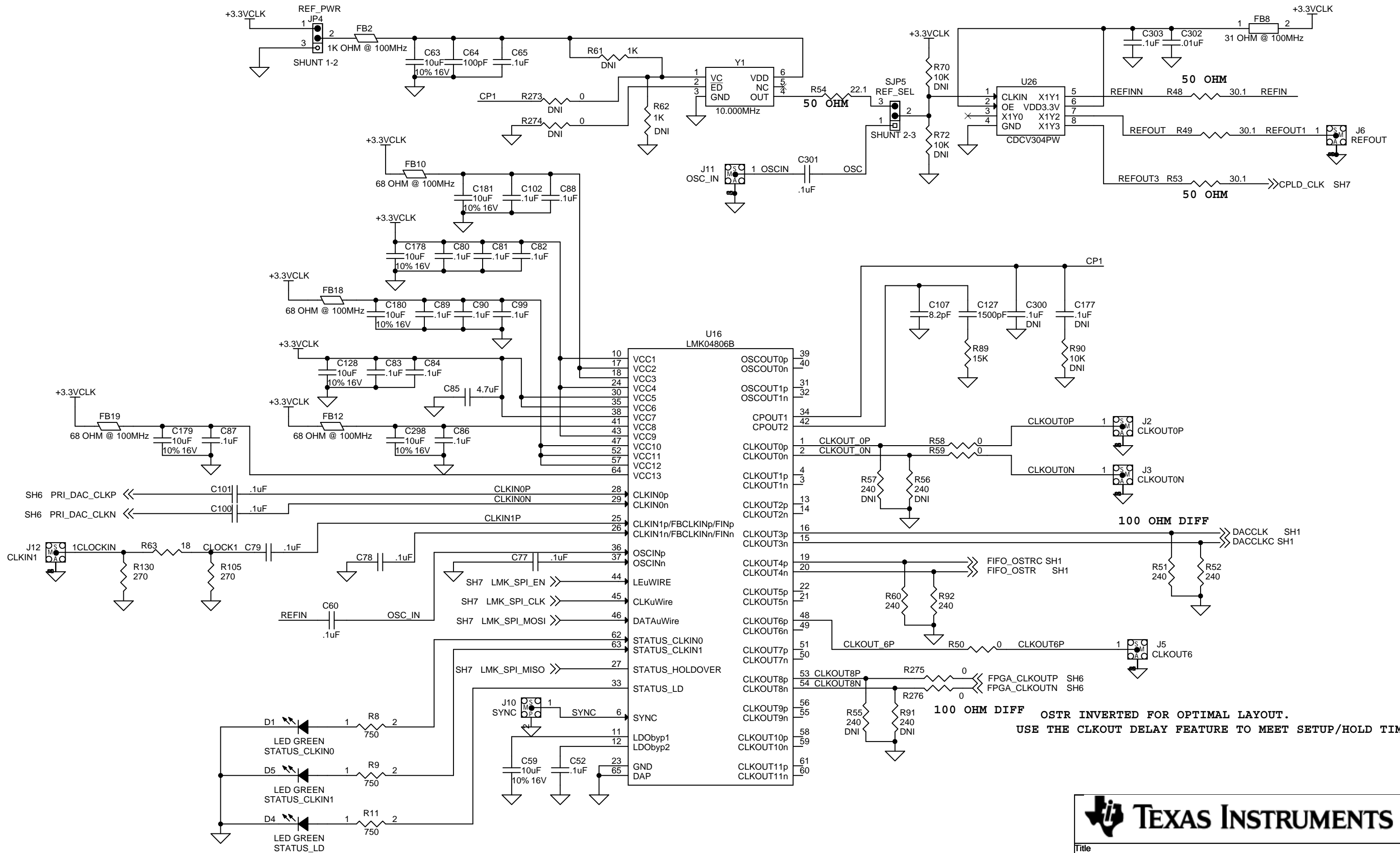
TOP SIDE ROUTE ONLY

TEXAS INSTRUMENTS

Title: **TSW3085 EVM**

Size **B** Document Number **DAC PWR** Rev **D**

Date: 09Jul12 Sheet 2 of 8

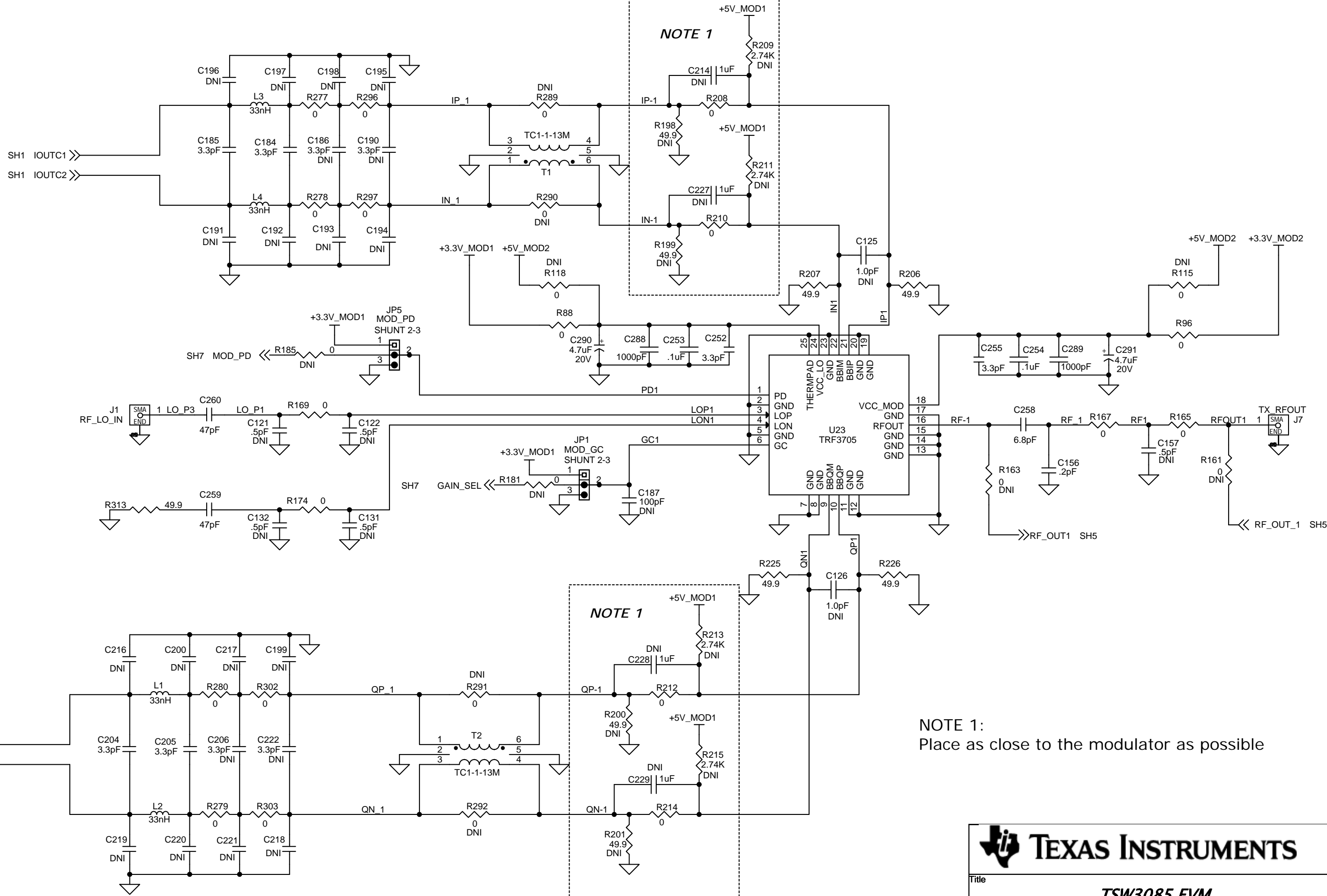


**OSTR INVERTED FOR OPTIMAL LAYOUT.
USE THE CLKOUT DELAY FEATURE TO MEET SETUP/HOLD TIME**

TEXAS INSTRUMENTS

Title: **TSW3085 EVM**

Size: B	Document Number: CLOCK	Rev: D
Date: 09Jul12	Sheet: 3 of 8	



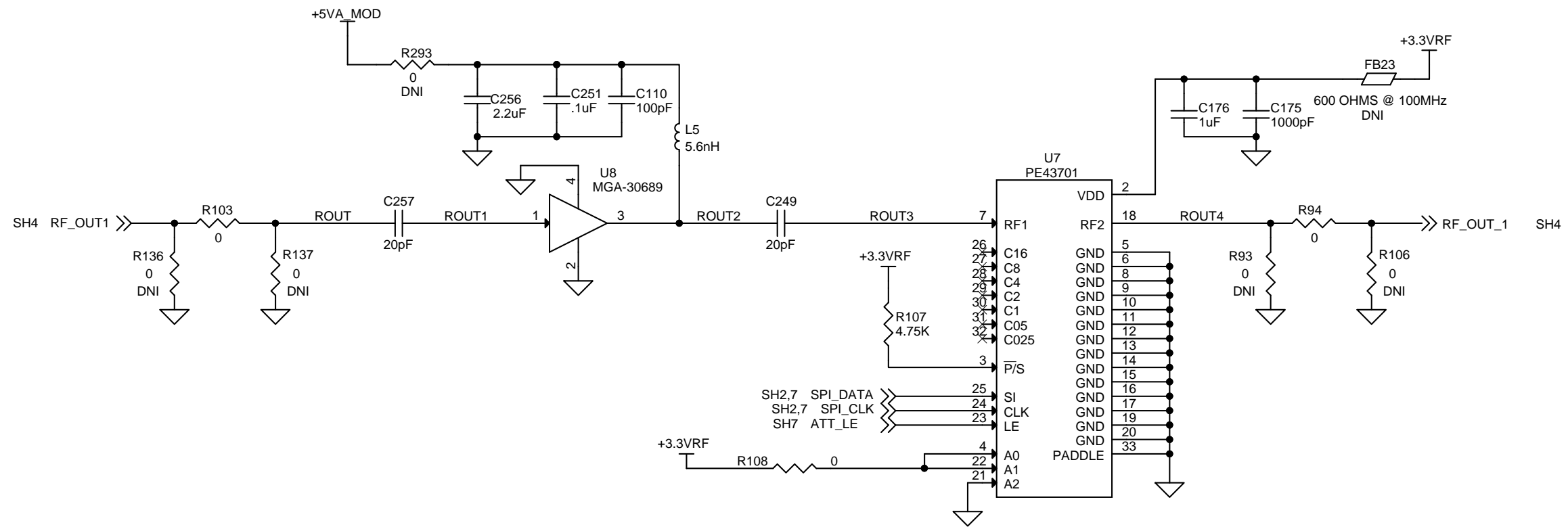
NOTE 1

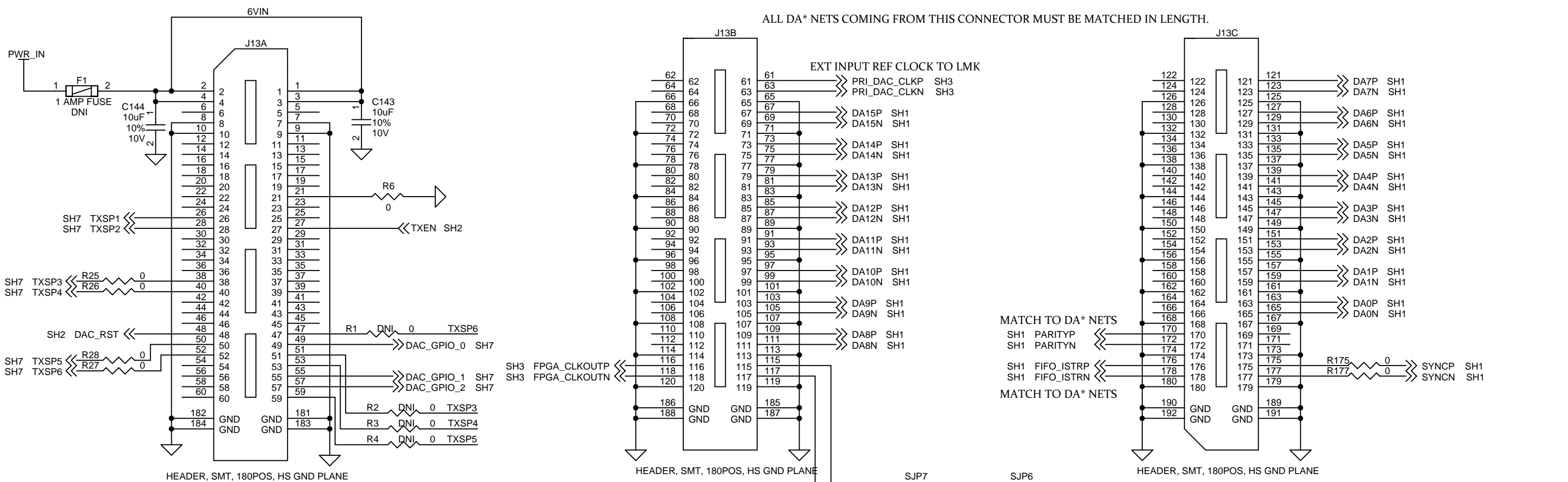
NOTE 1

NOTE 1:
Place as close to the modulator as possible

TEXAS INSTRUMENTS

Title		
TSW3085 EVM		
Size	Document Number	Rev
B	MODULATOR	D
Date:	09Jul12	Sheet 4 of 8





ALL DA* NETS COMING FROM THIS CONNECTOR MUST BE MATCHED IN LENGTH.

MATCH TO DA* NETS

SH1 PARITYP

SH1 PARITYN

SH1 FIFO_ISTRP

SH1 FIFO_ISTRN

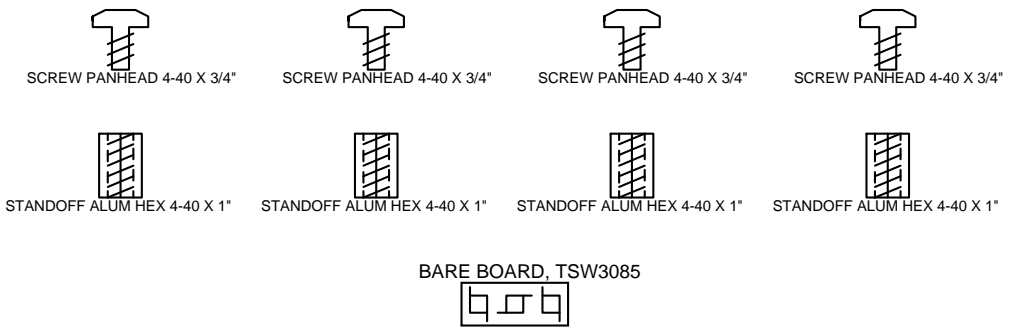
MATCH TO DA* NETS

DATACLK-P/N traces on top side.

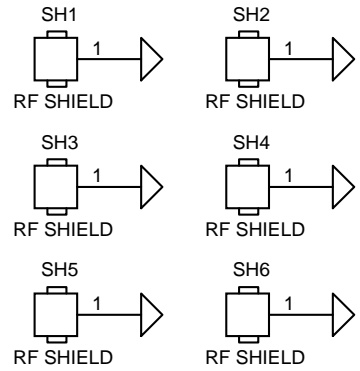
DATACLKP/N traces on top side.

DCLK-P/N traces are on the bottom side of the board and are 2" longer than DCLKP/N are topside traces

MECHANICAL PARTS



HOLES FOR THE RF SHIELD, QTY 1

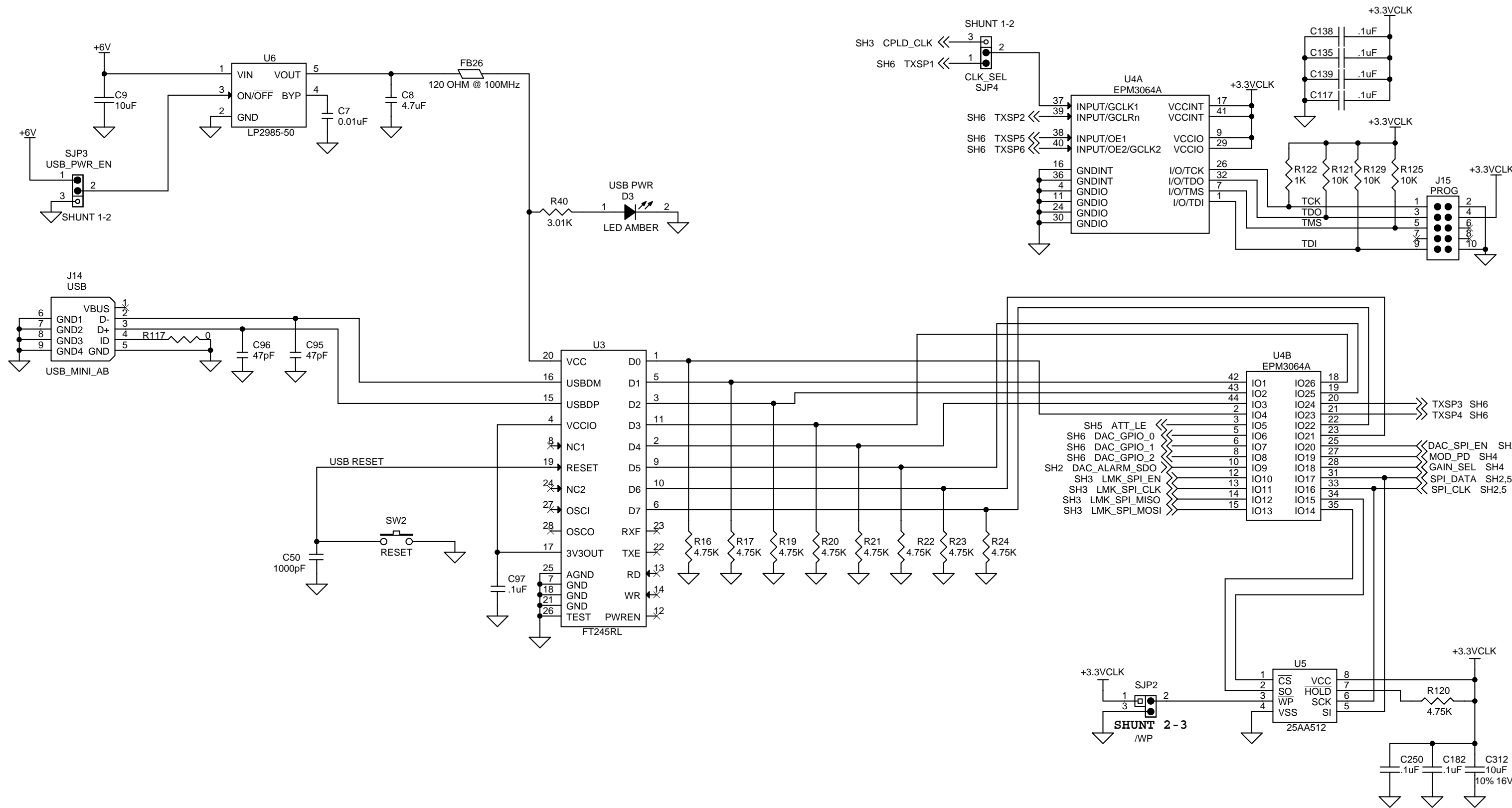


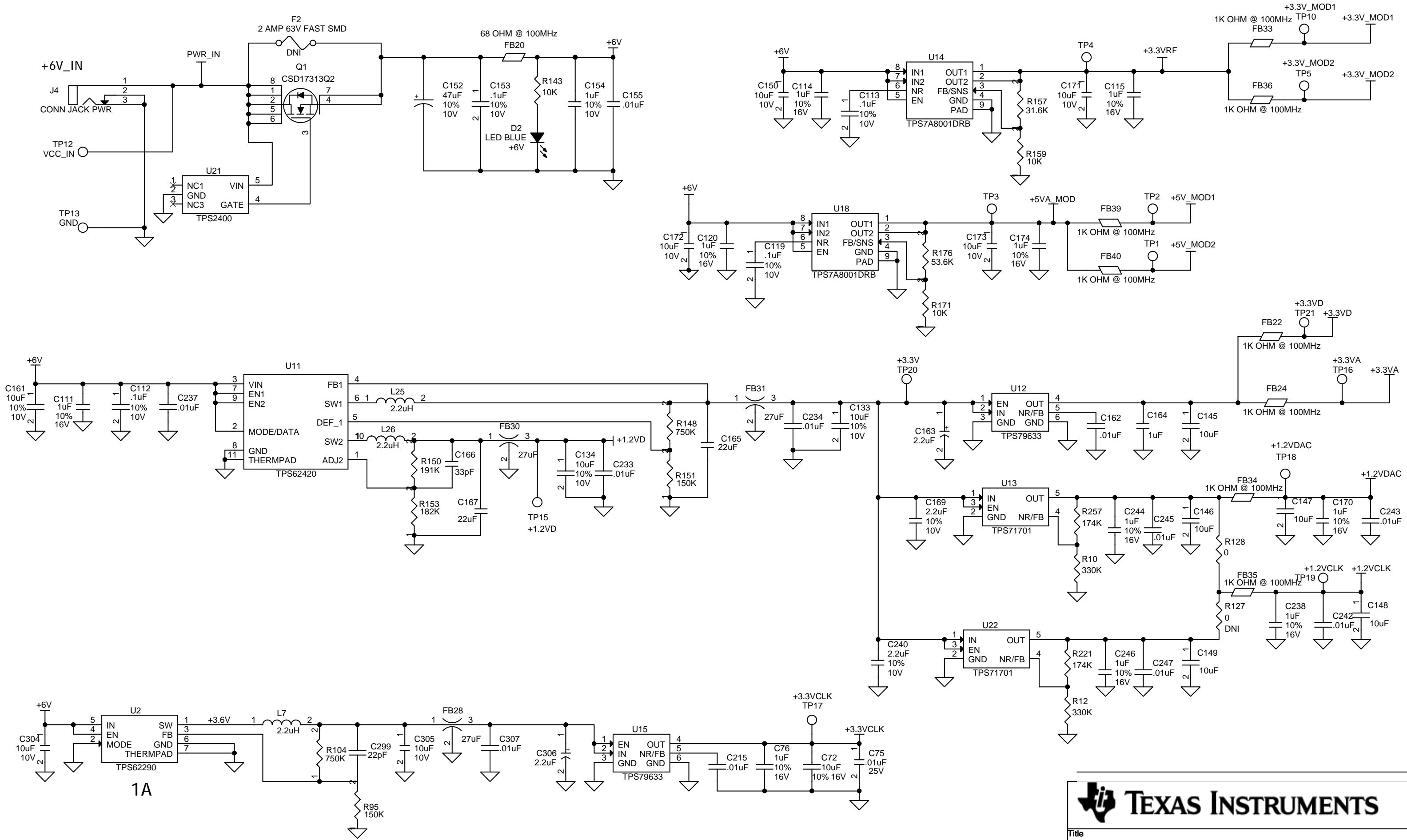
TEXAS INSTRUMENTS

Title: **TSW3085 EVM**

Size: **B** Document Number: **INTERFACE** Rev: **D**

Date: 09Jul12 Sheet 6 of 8





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